

**6 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY**
**NEW PRODUCT**
**Features**

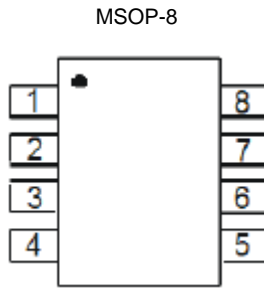
- IEC 61000-4-2 (ESD): Contact – ±8kV
- IEC 61000-4-5 (Lightning): 4A (8/20µs)
- 6 Channels of ESD Protection
- Low Channel Input Capacitance of 0.32pF max
- Typically Used at USB 3.0 and High Speed Ports in Any Electronic Product
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

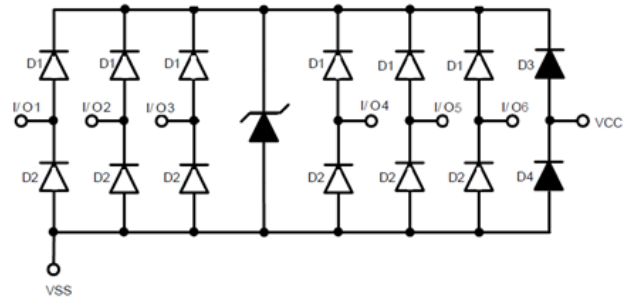
- Case: MSOP-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Terminals: NiPdAu over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 **Ⓔ4**
- Weight: 0.027 grams (Approximate)

| Pin# | Description |
|------|-------------|
| 1    | I/O1        |
| 2    | I/O2        |
| 3    | I/O3        |
| 4    | I/O4        |
| 5    | I/O5        |
| 6    | I/O6        |
| 7    | Vss         |
| 8    | Vcc         |

Pin Description



Top View

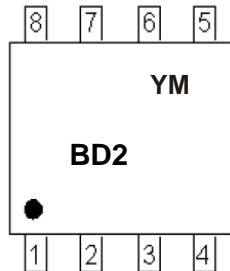


Device Schematic

**Ordering Information (Note 4)**

| Product        | Compliance | Marking | Reel size(inches) | Tape width(mm) | Quantity per reel |
|----------------|------------|---------|-------------------|----------------|-------------------|
| DT6250-06MR-13 | Standard   | BD2     | 13                | 12             | 2,500/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


BD2 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: A = 2013)  
 M = Month (ex: 9 = September)

## Date Code Key

| Year | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 |
|------|------|------|------|------|------|------|
| Code | A    | B    | C    | D    | E    | F    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                        | Symbol               | Value       | Unit | Conditions                                |
|---------------------------------------|----------------------|-------------|------|---|
| Peak Pulse Current, per IEC 61000-4-5 | I <sub>PP</sub>      | 4           | A    | I/O to V <sub>SS</sub> , 8/20μs           |
| ESD Protection – Contact Discharge    | V <sub>ESD_I/O</sub> | ±8          | kV   | IO to V <sub>SS</sub> , per IEC 61000-4-2 |
| Operating Temperature                 | T <sub>OP</sub>      | -40 to +85  | °C   | —   |
| Storage Temperature                   | T <sub>STG</sub>     | -55 to +150 | °C   | —   |

**Thermal Characteristics**

| Characteristic                                   | Symbol           | Value | Unit |
|--|------------------|-------|------|
| Power Dissipation (Note 5)                       | P <sub>D</sub>   | 500   | mW   |
| Thermal Resistance, Junction to Ambient (Note 5) | R <sub>θJA</sub> | 250   | °C/W |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                   | Symbol                                   | Min | Typ  | Max | Unit | Test Conditions   |
|----------------------------------|--|-----|------|-----|------|---|
| Reverse Working Voltage          | V <sub>RWM</sub>                         | —   | —    | 5.0 | V    | V <sub>CC</sub> to V <sub>SS</sub>                        |
| Reverse Leakage Current (Note 6) | I <sub>R_VCC</sub>                       | —   | —    | 2.5 | μA   | V <sub>CC</sub> = 5V, V <sub>CC</sub> to V <sub>SS</sub>  |
| Channel Leakage Current (Note 6) | I <sub>R_IO</sub>                        | —   | —    | 1.0 | μA   | V <sub>CC</sub> = 5V, any I/O to V <sub>SS</sub>          |
| Reverse Breakdown Voltage        | V <sub>BR</sub>                          | 6   | —    | —   | V    | I <sub>BV</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub> |
| Forward Voltage                  | V <sub>F</sub>                           | —   | 0.8  | 1.2 | V    | I <sub>F</sub> = 15mA, V <sub>SS</sub> to V <sub>CC</sub> |
| ESD Clamping Voltage             | V <sub>ESD_I/O</sub>                     | —   | 10   | —   | V    | TLP, 10A, tp = 100ns, I/O to V <sub>SS</sub>              |
|                                  | V <sub>ESD_VCC</sub>                     | —   | 9    | —   | V    | TLP, 10A, tp = 100ns, V <sub>CC</sub> to V <sub>SS</sub>  |
| Differential Resistance          | R <sub>DIF_I/O</sub>                     | —   | 0.35 | —   | Ω    | TLP, 10A, tp = 100ns, I/O to V <sub>SS</sub>              |
|                                  | R <sub>DIF_VCC</sub>                     | —   | 0.25 | —   | Ω    | TLP, 10A, tp = 100ns, V <sub>CC</sub> to V <sub>SS</sub>  |
| Channel Input Capacitance        | C <sub>I/O</sub>                         | —   | 0.32 | —   | pF   | V <sub>I/O</sub> = 2.5V, V <sub>CC</sub> = 5V, f = 1MHz   |
| Delta C <sub>I/O</sub>           | C <sub>I/OMAX</sub> -C <sub>I/OMIN</sub> | —   | 0.05 | —   | pF   | C <sub>I/OMAX</sub> -C <sub>I/OMIN</sub>                  |

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
  6. Short duration pulse test used to minimize self-heating effect.

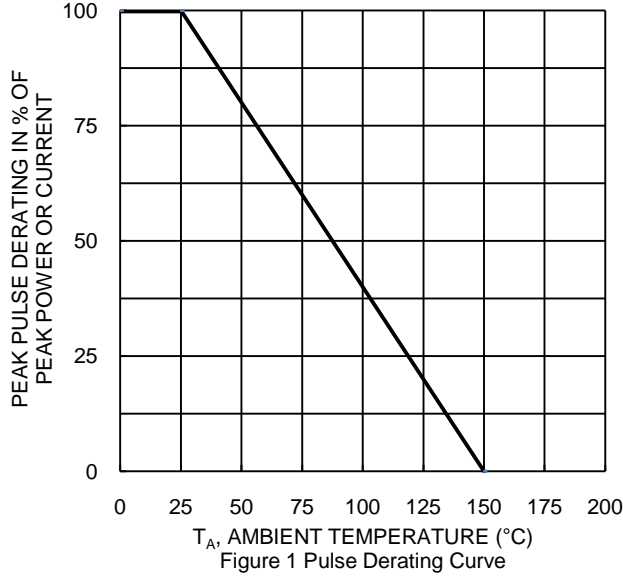


Figure 1 Pulse Derating Curve

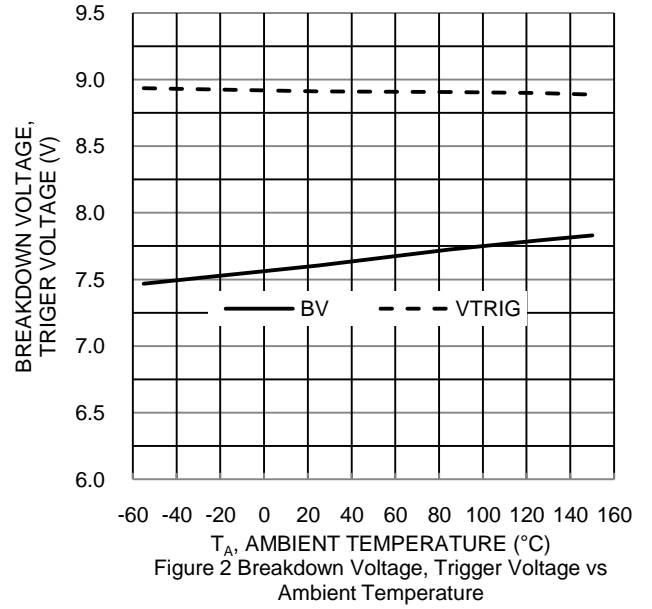


Figure 2 Breakdown Voltage, Trigger Voltage vs Ambient Temperature

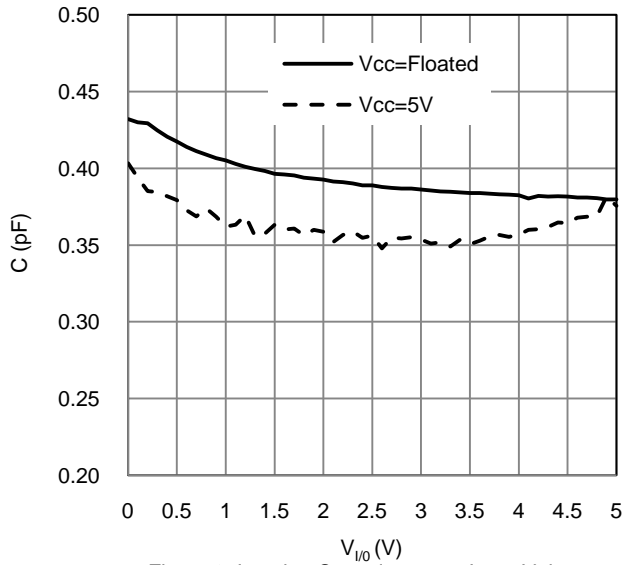


Figure 3 Junction Capacitance vs Input Voltage

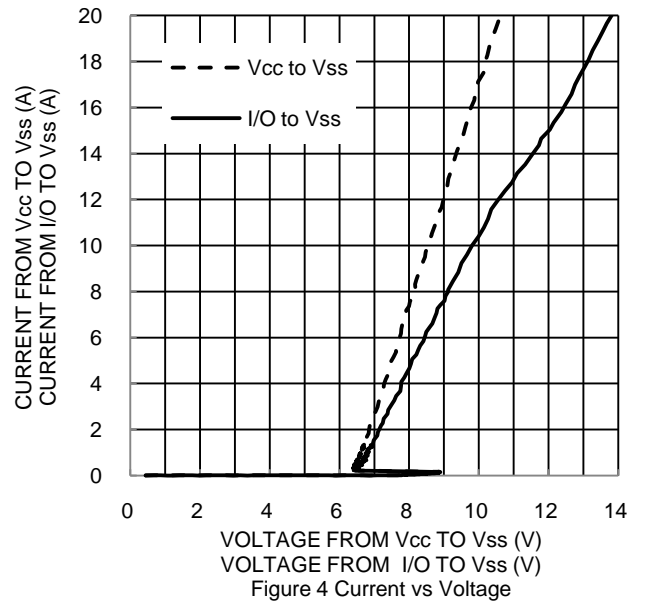


Figure 4 Current vs Voltage

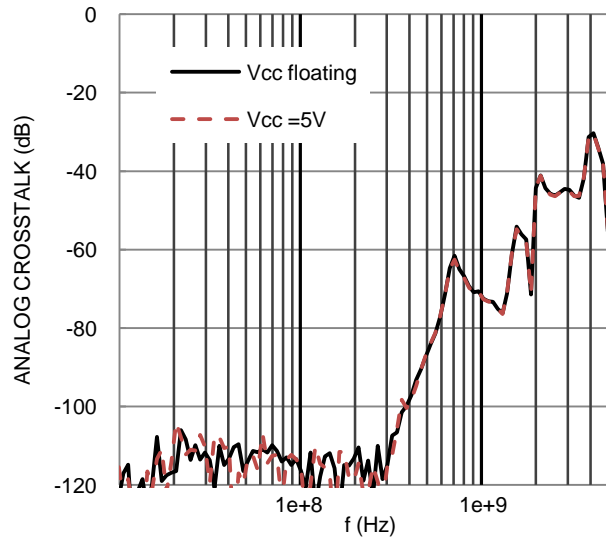


Figure 5 Analog Crosstalk Measurement

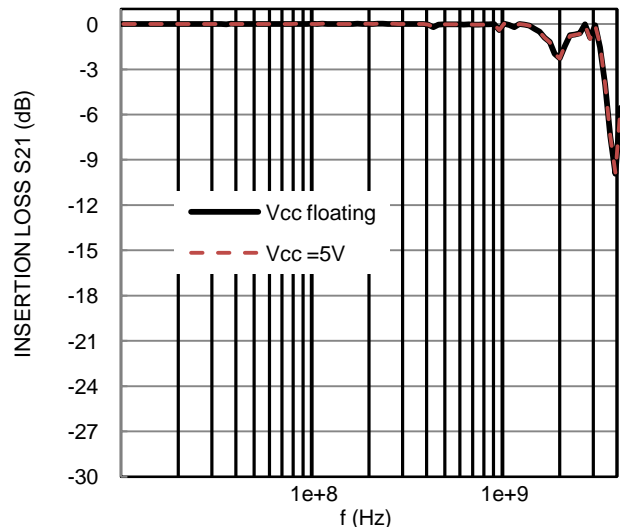
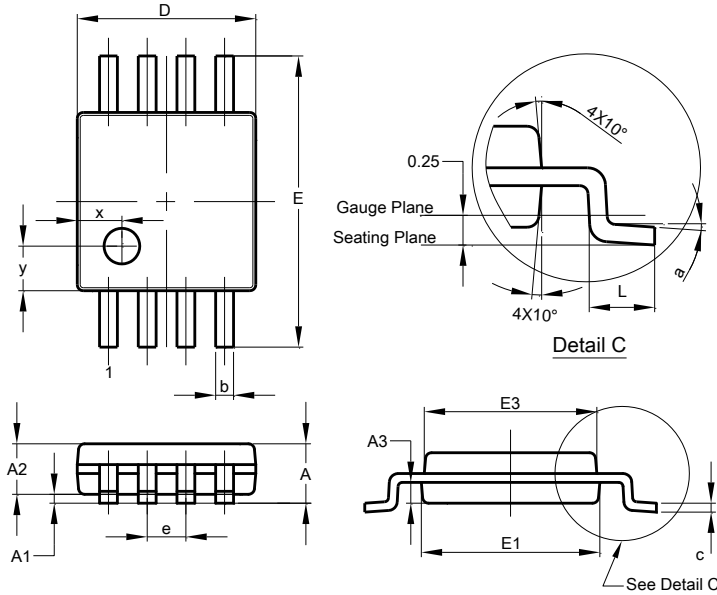


Figure 6 S21(dB) Attenuation Measurement

**Package Outline Dimensions**

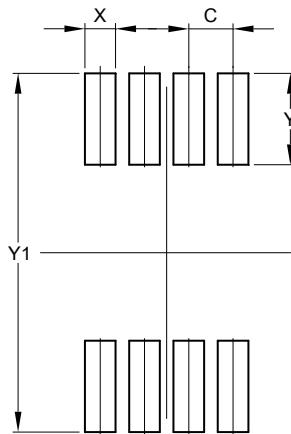
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| MSOP-8                      |      |      |       |
|-----------------------------|------|------|-------|
| Dim                         | Min  | Max  | Typ   |
| A                           | -    | 1.10 | -     |
| A1                          | 0.05 | 0.15 | 0.10  |
| A2                          | 0.75 | 0.95 | 0.86  |
| A3                          | 0.29 | 0.49 | 0.39  |
| b                           | 0.22 | 0.38 | 0.30  |
| c                           | 0.08 | 0.23 | 0.15  |
| D                           | 2.90 | 3.10 | 3.00  |
| E                           | 4.70 | 5.10 | 4.90  |
| E1                          | 2.90 | 3.10 | 3.00  |
| E3                          | 2.85 | 3.05 | 2.95  |
| e                           | -    | -    | 0.65  |
| L                           | 0.40 | 0.80 | 0.60  |
| a                           | 0°   | 8°   | 4°    |
| x                           | -    | -    | 0.750 |
| y                           | -    | -    | 0.750 |
| <b>All Dimensions in mm</b> |      |      |       |

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C          | 0.650         |
| X          | 0.450         |
| Y          | 1.350         |
| Y1         | 5.300         |

NEW PRODUCT

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